



Pin Definition: 1. Gate 2. Drain 3. Source

PRODUCT SUMMARY

	V _{DS} (V)	R _{DS(on)} (Ω)	I _D (A)	
_	500	0.44 @ V _{GS} =10V	14	

General Description

The TSM15N50 N-Channel enhancement mode Power MOSFET is produced by planar stripe DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency switch mode power supply, electronic lamp ballast based on half bridge.

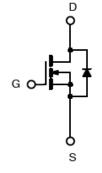
Features

- Low $R_{DS(ON)}$ 0.44 Ω (Max.)
- Low gate charge typical @ 39nC (Typ.)
- Improve dv/dt capability

Ordering Information

Part No.	Package	Packing		
TSM15N50CZ C0	TO-220	50pcs / Tube		
TSM15N50CZ C0G	TO-220	50pcs / Tube		
TSM15N50CI C0	ITO-220	50pcs / Tube		
TSM15N50CI C0G	ITO-220	50pcs / Tube		

Block Diagram



N-Channel MOSFET

Note: "G" denotes Halogen Free Product.

Absolute Maximum Rating (Ta = 25°C unless otherwise noted)

Parameter	Symbol	Limit	Unit	
Drain-Source Voltage	V _{DS}	500	V	
Gate-Source Voltage	V _{GS}	±30	V	
Continuous Drain Current($T_C=25^{\circ}C$)	Ι _D	14	А	
Pulsed Drain Current *	I _{DM}	56	А	
Peak Diode Recovery dv/dt (Note 3)	dv/dt	4.5	V/ns	
Single Pulse Avalanche Energy (Note 2)	E _{AS}	630	mJ	
Avalanche Current (Repetitive) (Note 1)	I _{AR}	14	А	
Repetitive Avalanche Energy (Note 1)	E _{AR}	23.1	mJ	
Operating Junction Temperature	TJ	150	°C	
Storage Temperature Range	T _{STG}	-55 to +150	°C	

* Limited by maximum junction temperature



Thermal Performance

Parameter	Symbol	TO-220	ITO-220	Unit	
Thermal Resistance - Junction to Case	RƏ _{JC}	0.54	2.34	00.000	
Thermal Resistance - Junction to Ambient	RƏ _{JA}	62.5		°C/W	

Notes: Surface mounted on FR4 board t \leq 10sec

Electrical Specifications (Tc = 25°C unless otherwise noted)

Parameter	Conditions	Symbol	Min	Тур	Max	Unit
Static						
Drain-Source Breakdown Voltage	$V_{GS} = 0V, I_{D} = 250uA$	BV _{DSS}	500			V
Drain-Source On-State Resistance	$V_{GS} = 10V, I_{D} = 7.0A$	R _{DS(ON)}		0.35	0.44	Ω
Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = 250 \text{uA}$	V _{GS(TH)}	2.0		4.0	V
Zero Gate Voltage Drain Current	$V_{DS} = 500V, V_{GS} = 0V$	I _{DSS}			1	uA
Gate Body Leakage	$V_{GS} = \pm 30V, V_{DS} = 0V$	I _{GSS}			±100	nA
Forward Transconductance	$V_{DS} = 30V, I_{D} = 7.0A$	g _{fs}		10		S
Diode Forward Voltage	$I_{S} = 14A, V_{GS} = 0V$	V_{SD}			1.5	V
Dynamic ^b						
Total Gate Charge		Qg		39		
Gate-Source Charge	$V_{DS} = 400V, I_D = 14A,$	Q_gs		11		nC
Gate-Drain Charge	– V _{GS} = 10V	Q_gd		8.6		
Input Capacitance		C _{iss}		2263		
Output Capacitance	$V_{DS} = 25V, V_{GS} = 0V,$ = f = 1.0MHz	C _{oss}		211		pF
Reverse Transfer Capacitance		C _{rss}		6.4		
Switching ^c						
Turn-On Delay Time		t _{d(on)}		65		
Turn-On Rise Time	$V_{DD} = 250V, I_D = 14A,$	t _r		55		~~~
Turn-Off Delay Time	$R_{G} = 25\Omega$	t _{d(off)}		144		nS
Turn-Off Fall Time		t _f		58		
Reverse Recovery Time	$V_{GS} = 0V, I_{S} = 14A,$	t _{fr}		381		nS
Reverse Recovery Charge	dI _F /dt = 100A/us	Q _{fr}		4.4		uC

Notes:

1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

2. Max Rating E_{AS} Test Condition: V_{DD} = 50V, I_{AS}=14A, L=5.9mH, R_G=25 Ω , Starting T_J=25 $^{\circ}$ C

3. Guaranteed 100% E_{AS} Test Condition: V_{DD} = 50V, I_{AS}=14A, L=1mH, R_G=25 Ω , Starting T_J=25 $^{\circ}$ C

4. $I_{SD} \leq 14A$, di/dt $\leq 200A/uS$, $V_{DD} \leq BV$, Starting $T_J=25^{\circ}C$

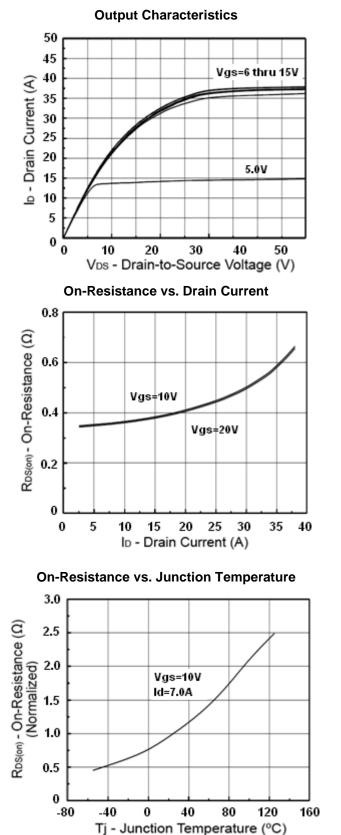
5. Pulse test: pulse width \leq 300uS, duty cycle \leq 2%

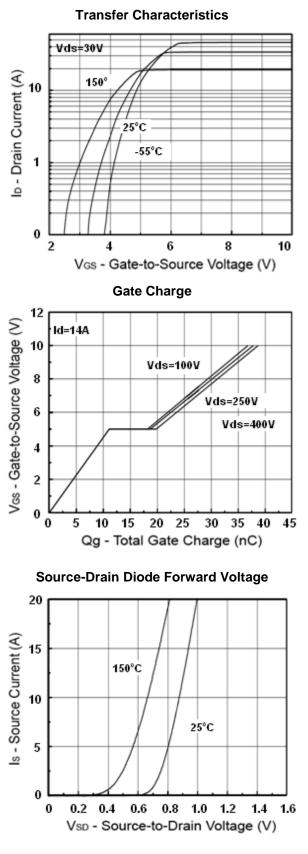
6. b For design reference only, not subject to production testing.

7. c Switching time is essentially independent of operating temperature.



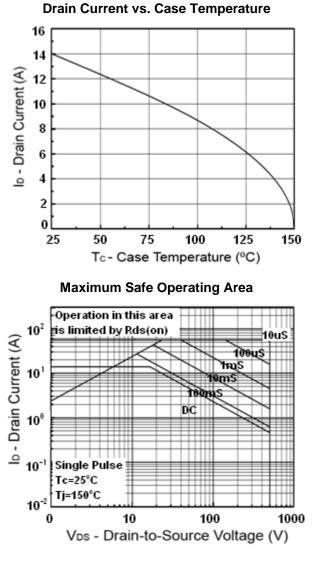




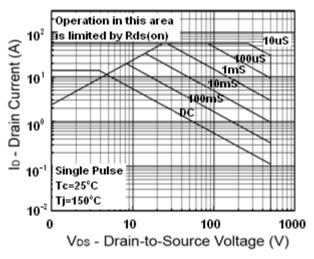


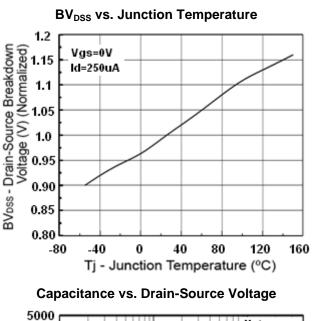


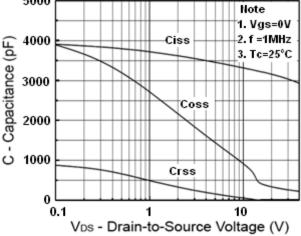
Electrical Characteristics Curve (Ta = 25°C, unless otherwise noted)



Maximum Safe Operating Area (ITO-220)

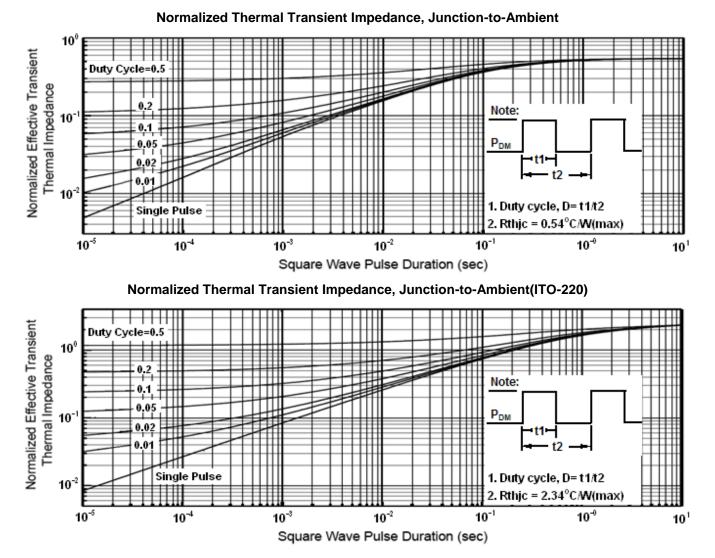






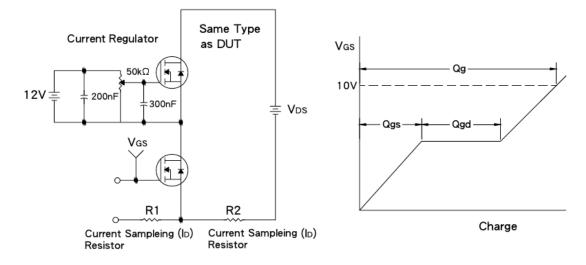


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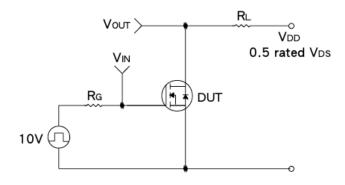


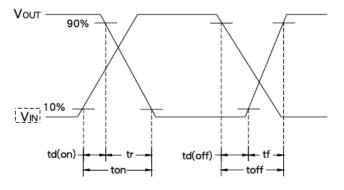


Gate Charge Test Circuit & Waveform

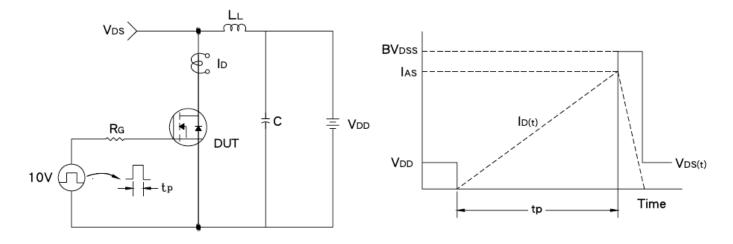


Resistive Switching Test Circuit & Waveform



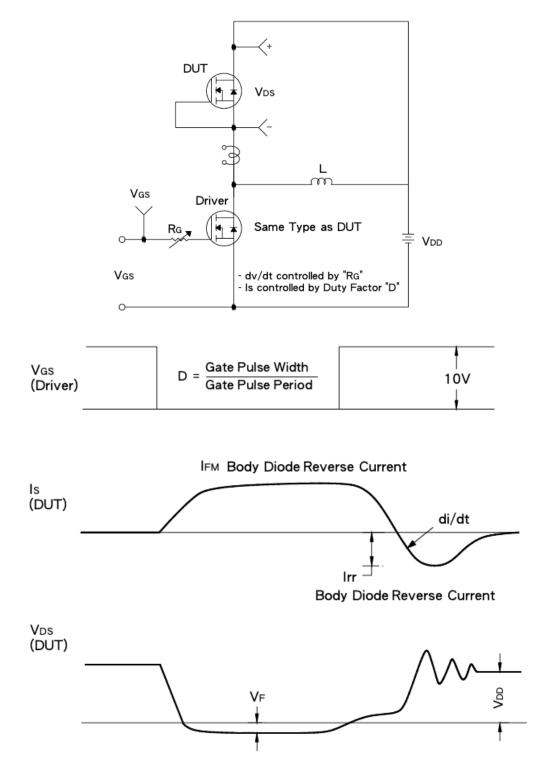


E_{AS} Test Circuit & Waveform



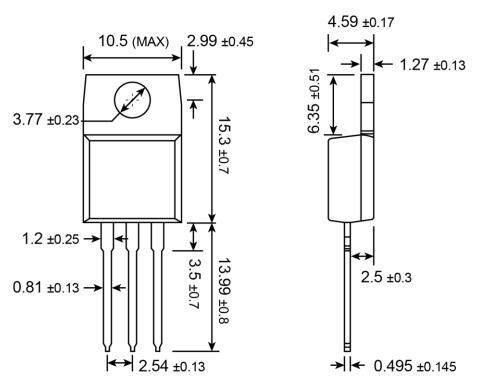


Diode Reverse Recovery Time Test Circuit & Waveform



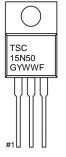


TO-220 Mechanical Drawing



Unit: Millimeters

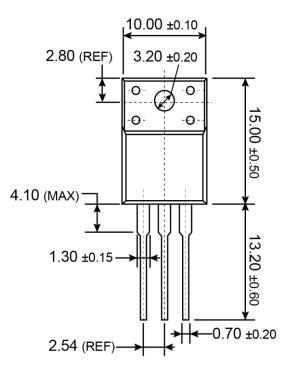
MARKING DIAGRAM

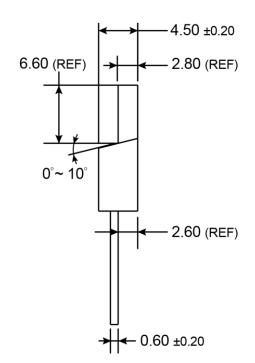


- G = Halogen Free
- Y = Year Code
- WW = Week Code (01~52)
 - **F** = Factory Code



ITO-220 Mechanical Drawing





Unit: Millimeters

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